| Substitute Form PTO-1449 (Modified) | U.S. Department of Commerce Patent and Trademark Office | Attorney's Docket No. 06618-917001 | Application No. 10-678,359 |
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| **Information Disclosure Statement by Applicant** (Use several sheets if necessary) (37 CFR §1.98(b)) | | Applicant Eui-Hyeok Yang | |
| | | Filing Date October 2, 2003 | Group Art Unit 1763 |

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| George Goudreau | 2-06' |

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| Substitute Form PTO-1449 (Modified) | U.S. Department of Commerce Patent and Trademark Office | Attorney's Docket No. 06618-917001 | Application No. 10-678,359 |
|---|---|---|---|
| **Information Disclosure Statement by Applicant** (Use several sheets if necessary) (37 CFR §1.98(b)) | | Applicant Eui-Hyeok Yang | |
| | | Filing Date October 2, 2003 | Group Art Unit 1763 |

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